

## WHAT IS CLAIMED IS:

1. A semiconductor laser device comprising:

a semiconductor laser element;

5 a generally circular stem to which said semiconductor laser element is mounted, said stem having at least one notch at an outer peripheral part thereof; and

a cap covering said semiconductor laser element, said cap having a flange for welding to an upper surface of the stem, wherein

10 said flange of the cap is provided with at least one cut-off portion; and

when said cap is in a state welded to the stem, said or each cut-off portion of the flange is positioned in a region of the stem in which no notch is present.

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2. The semiconductor laser device according to claim 1, wherein the number of notches provided at the outer peripheral part of the stem and the number of cut-off portions of the flange are three or more.

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3. The semiconductor laser device according to claim 1, wherein a difference between a radius of the circular stem and that of the flange is 0.4 mm or less.

4. The semiconductor laser device according to claim 1, wherein a venthole is provided in a side surface of the cap at a location corresponding to said cut-off portion.

5 5. A method for producing the semiconductor laser device of claim 1, wherein when welding a flange of a cap, which is provided with at least one cut-off portion, to an upper surface of a generally circular stem having at least one notch at an outer peripheral part thereof, the method  
10 comprises:

positioning the stem using said at least one notch of the stem; and

positioning the cap using said at least one cut-off portion of the flange of the cap such that said or each  
15 cut-off portion is located in a region having no notch of the stem.

6. The method according to claim 5, wherein said flange has a plurality of cut-off portions, and partial  
20 flange portions into which the flange is divided by these cut-off portions are welded to the stem by independent electrodes and power supplies.